

Capabilities

Item	Processing Capability
Layer Count	2-48 layers
Material	FR4 Materials: Shengyi, Lianxiang, Nan Ya, Jianyuan, Huazheng series High Frequency Materials: Rogers, Arlon, Taconic, AGC, Wang Ling, Ruilong Fushi De series High Speed Materials: Matsushita, Taixiang, Lianxiang, Tai Guang, Shengyi series
Maximum Finished Size	Double-sided: 630mm x 1200mm Multi-layer: 590 mm x 660 mm
Board Thickness	0.2 mm-6.0 mm
Maximum Copper Thickness	Inner layer 6oz, outer layer 10oz
Minimum Drilling Hole	0.15 mm
Board Thickness to Hole Diameter Ratio	20:01
Minimum Width/Spacing	2.5 mil/2.5 mil
Minimum Impedance Bridge	Green 2 mil, Mixed 4 mil
Via Diameter	0.2 mm - 1.0 mm
Impedance Tolerance	± 6%
Impedance Color	Green/White/Black/Red/Yellow/Blue/Purple/Orange/Coffee
Special Process	Thick copper clad, embedded copper clad, high frequency foam clad, high frequency mixed clad, buried hole, press-fit hole, semi-hole, step hole, resin-filled hole, metal edge clad
Surface Treatment	OSP/Lead-free hasl/Lead-free spray tin/Immersion gold/Electroplating (hard gold or soft gold)/Solder mask/Nickel/Tin/Gold plating/OSP